

## **REMARKS**

### **Claim Rejections 35 U.S.C. § 102 (b)/(e)**

#### **Claims 14-23**

The Examiner has rejected claims 14-17 and 19-21 under 35 U.S.C. § 102 (b) as being anticipated by Casson et al. (US 5,261,593).

The Examiner has rejected claims 14-17, 19, and 21 under 35 U.S.C. § 102 (b) as being anticipated by Sweitzer et al. (US 5,615,477).

The Examiner has rejected claims 14-17, 19, and 21 under 35 U.S.C. § 102 (b) as being anticipated by Koopman et al. (US 5,992,729).

The Examiner has rejected claims 14-17 and 19-21 under 35 U.S.C. § 102 (e) as being anticipated by Lin et al. (US 6,548,393).

The Examiner has rejected claims 14-17 and 20-23 under 35 U.S.C. § 102 (e) as being anticipated by Farooq et al. (US 6,541,305).

The Examiner has rejected claims 14-20 under 35 U.S.C. § 102 (e) as being anticipated by Chandran et al. (US 2005/0116329).

Applicants respectfully disagree with the Examiner. Applicants have amended claims 14 and 16. Support is provided by paragraphs [0026]-[0031] in the specification.

Claim 14, as amended, claims an apparatus including: a magnetron (190), the magnetron capable of generating microwave energy (180); a waveguide (195) located near the magnetron, the waveguide coupled to an input aperture, the waveguide capable of transmitting the microwave energy; a stirrer (210) located near the waveguide, the stirrer capable of linear and rotational motion, the stirrer formed of a material that reflects the microwave energy, the stirrer to mix the microwave energy;

a susceptor (200) located near the stirrer, the susceptor capable of linear motion and rotational motion, the susceptor formed of a material that does not absorb the microwave energy, the susceptor to further mix the microwave energy; and a self-aligned mechanical joint (225) held by the susceptor, the self-aligned mechanical joint exposed to the microwave energy, the self-aligned mechanical joint including: a bump (155) located on a die (100), the die capable of absorbing the microwave energy, the microwave energy capable of being transformed into heat by molecular excitation; and a solder alloy located on a substrate (170), the solder alloy capable of reflow by the heat through conduction from the bump. See Figures 2a-2b.

None of the 6 references cited by the Examiner teaches each and every element of Applicants' invention, as claimed in claim 14, as amended. Consequently, none of the 6 references anticipates Applicants' invention.

Claims 15-23 are dependent on claim 14, as amended, and, thus, are also not anticipated by any of the 6 references cited by the Examiner.

In view of the foregoing, Applicants respectfully request the Examiner to withdraw the rejections to claims 14-23 under 35 U.S.C. § 102 (b)/(e).

### **CONCLUSION**

Applicants believe that all claims pending, including claims 14-23, are now in condition for allowance so such action is earnestly solicited at the earliest possible date.


Pursuant to 37 C.F.R. 1.136(a)(3), Applicant hereby requests and authorizes the U.S. Patent and Trademark Office to treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time.

Should there be any additional charge or fee, including a Request for Continued Examination, an extension of time fee, or other fees under 37 C.F.R. 1.16 and 1.17, please charge Deposit Account No. 02-2666.

If a telephone interview would in any way expedite the prosecution of this application, the Examiner is invited to contact the undersigned at (408) 720-8300.

Respectfully submitted,  
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN

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